

GHB-PLCC-G

Features

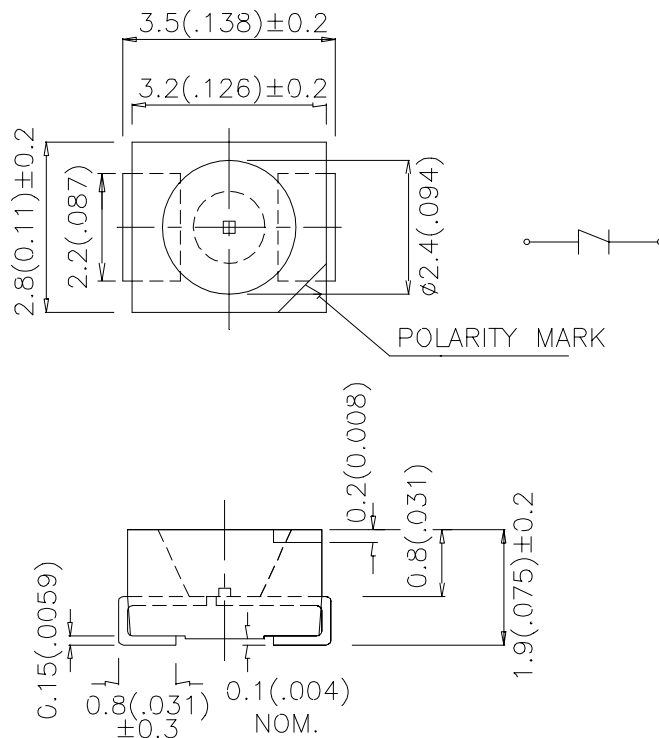
- ✓SINGLE COLOR.
- ✓SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- ✓IDEAL FOR BACKLIGHTING.
- ✓AVAILABLE ON TAPE AND REEL.
- ✓PACKAGE : 1500PCS / REEL.

Description

The Green source color devices are made with InGaN on SiC Light Emitting Diode.

3.5x2.8 mm SMD CHIP LED LAMP

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is 0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	I _v (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	
GHB-PLCC-G	GREEN (InGaN)	WATER CLEAR	110	280	120°

Note:

1. 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25 C

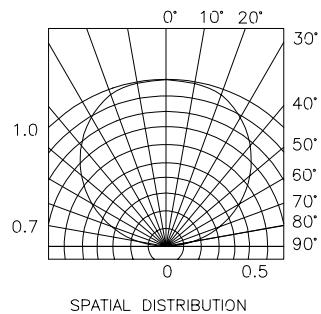
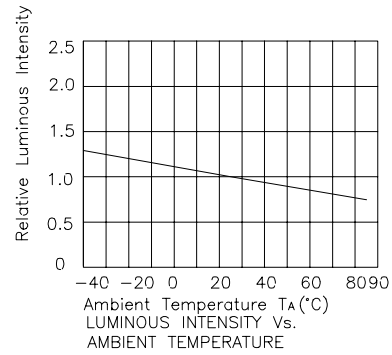
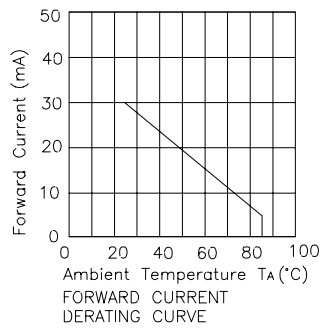
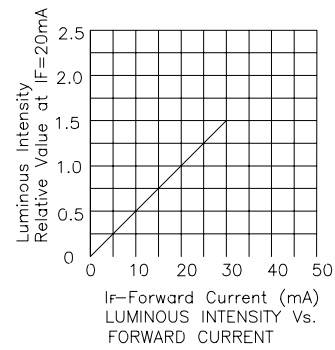
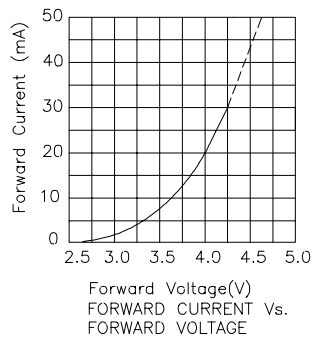
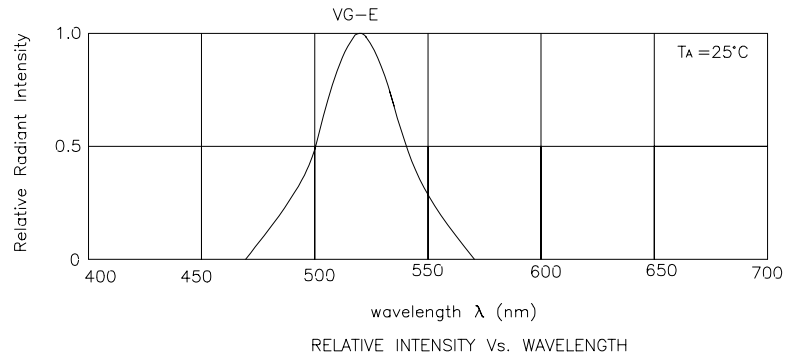
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
peak	Peak Wavelength	Green	518		nm	I _F =20mA
D	Dominate Wavelength	Green	525		nm	I _F =20mA
1/2	Spectral Line Half-width	Green	36		nm	I _F =20mA
C	Capacitance	Green	50		pF	V _F =0V;f=1MHz
V _F	Forward Voltage	Green	4.0	4.5	V	I _F =20mA
I _R	Reverse Current	Green		10	uA	V _R = 5V

Absolute Maximum Ratings at T_A=25 C

Parameter	Green	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40 C To +85 C	

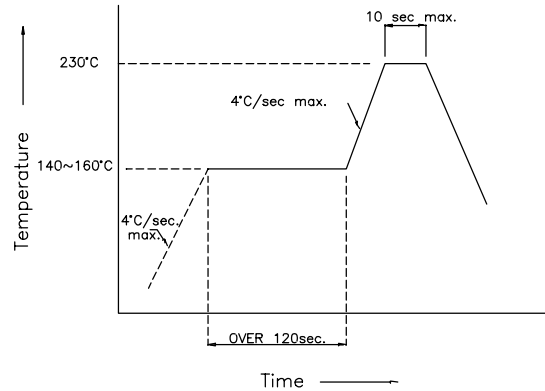
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

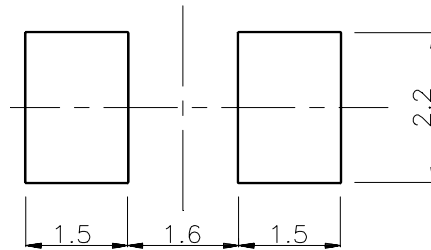


SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

